

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jing-Cheng Lin</td> <td>08/02/2011</td> </tr> <tr> <td>Chin-Chuan Chang</td> <td>08/02/2011</td> </tr> <tr> <td>Jui-Pin Hung</td> <td>08/02/2011</td> </tr> <tr> <td>Szu Wei Lu</td> <td>08/02/2011</td> </tr> <tr> <td>Shin-Puu Jeng</td> <td>08/04/2011</td> </tr> <tr> <td>Chen-Hua Yu</td> <td>08/02/2011</td> </tr> </tbody> </table>		Name	Execution Date	Jing-Cheng Lin	08/02/2011	Chin-Chuan Chang	08/02/2011	Jui-Pin Hung	08/02/2011	Szu Wei Lu	08/02/2011	Shin-Puu Jeng	08/04/2011	Chen-Hua Yu	08/02/2011
Name	Execution Date														
Jing-Cheng Lin	08/02/2011														
Chin-Chuan Chang	08/02/2011														
Jui-Pin Hung	08/02/2011														
Szu Wei Lu	08/02/2011														
Shin-Puu Jeng	08/04/2011														
Chen-Hua Yu	08/02/2011														
RECEIVING PARTY DATA															
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>Taiwan Semiconductor Manufacturing Company, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. 6</td> </tr> <tr> <td>Internal Address:</td> <td>Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77 R.O.C.</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	Street Address:	No. 8, Li-Hsin Rd. 6	Internal Address:	Science-Based Industrial Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77 R.O.C.		
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.														
Street Address:	No. 8, Li-Hsin Rd. 6														
Internal Address:	Science-Based Industrial Park														
City:	Hsin-Chu														
State/Country:	TAIWAN														
Postal Code:	300-77 R.O.C.														
PROPERTY NUMBERS Total: 1															
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13208197</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13208197										
Property Type	Number														
Application Number:	13208197														
CORRESPONDENCE DATA															
<p>Fax Number: (972)732-9218</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 972-732-1001</p> <p>Email: edwards@slater-matsil.com</p> <p>Correspondent Name: Slater & Matsil, L.L.P.</p> <p>Address Line 1: 17950 Preston Road</p> <p>Address Line 2: Suite 1000</p> <p>Address Line 4: Dallas, TEXAS 75252</p>															
ATTORNEY DOCKET NUMBER:	TSM11-0327														

CH \$40.00 13208197

501625076

PATENT
REEL: 026743 FRAME: 0710

NAME OF SUBMITTER:

Kasey Edwards

Total Attachments: 2

source=TSM11-0327_Assignment#page1.tif

source=TSM11-0327_Assignment#page2.tif

ATTORNEY DOCKET NO.
TSM11-0327

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and


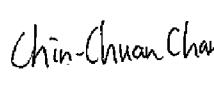
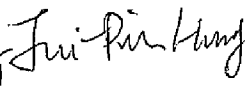
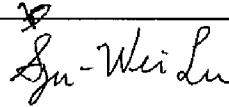
WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Molding Wafer Chamber			
SIGNATURE OF INVENTOR AND NAME	 Jing-Cheng Lin	 Chin-Chuan Chang	 Jui-Pin Hung	 Szu Wei Lu
DATE	8/2 '11	8/2 2011	2011/8/2	2011/8/2
RESIDENCE (City, County, State)	Hsin-Chu, Taiwan	Zhudong Township, Taiwan	Hsin-Chu, Taiwan	Hsin-Chu, Taiwan

ATTORNEY DOCKET NO.
TSM11-0327

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and



WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Molding Wafer Chamber			
SIGNATURE OF INVENTOR AND NAME	 Shin-Puu Jeng	 Chen-Hua Yu		
DATE	8/4/2012	8/2/11		
RESIDENCE (City, County, State)	Hsin-Chu, Taiwan	Hsin-Chu, Taiwan		